

CLAIMS

What is claimed is:

Sub 131
1. An interconnection element comprising:
a first element material adapted to be coupled to a
substrate; and
a second element material coupled to the first element
material,
wherein one of the first element material and the second
element material comprises a material having a transformable
property such that upon transformation, a shape of the
interconnection element is modified.

Cont Sub 131
2. The interconnection element of claim 1, wherein the
interconnection element is of a size suitable for directly
contacting a semiconductor device.

3. The interconnection element of claim 1, wherein a
transformation of the one of the first element material and
the second element material is irreversible.

Sub 131
4. The interconnection element of claim 1, wherein the
transformable property is such that a first volume of the
material is adapted to be transformed to a different second
volume.

Cont Sub 131
5. The interconnection element of claim 4, wherein the
first element material and the second element material are
arranged in a configuration such that the second element
material overlies the first element material and the first
volume of the second element material is greater than the
second volume.

6. The interconnection element of claim 4, wherein the
first element material is thermally stable and a
transformation of the second element material from the first

4 volume to the second volume is a result of exposing the
5 second element material to heat.

1 7. The interconnection element of claim 6, wherein the
2 transformation comprises at least about 90 percent of the
3 transformable volume change of the second element material.

1 8. The interconnection element of claim 1, wherein each of
2 the first element material and the second element material
3 have a transformable property.

1 9. The interconnection element of claim 1, wherein at least
2 one of the first element material and the second element
3 material are introduced by plating.

1 10. The interconnection element of claim 1, wherein at least
2 one of the first element material and the second element
3 material are introduced by sputtering.

1 11. The interconnection element of claim 1, wherein at least
2 one of the first element material and the second element
3 material are introduced by electroless plating.

1 12. The interconnection element of claim 3, wherein the
2 first element material comprises palladium or its alloy.

Sub 13. The interconnection element of claim 4, wherein the
2 first element material is an alloy comprising
3 palladium/cobalt and the activation layer comprises one of
4 copper and nickel.

1 14. The interconnection element of claim 13, wherein the
2 second element material further comprises nickel.

1 15. The interconnection element of claim 13, wherein the
2 second element material comprises a nickel alloy.

1 16. The interconnection element of claim 1, wherein the one
2 of the first element material and the second element material
3 comprises a shape memory alloy.

1 17. The interconnection element of claim 16, wherein the
2 second element material comprises the shape memory alloy and
3 overlies the first element material.

1 18. The interconnection element of claim 1, wherein the
2 transformable property is a stress and the transformation
3 reduces the magnitude of the stress of the material.

1 19. The interconnection element of claim 18, wherein the
2 first element material comprises the material having the
3 transformable property and the second element material has a
4 tensile stress, wherein upon transformation, the deformation
5 comprises a response to the tensile stress of the second
6 element material.

1 20. The interconnection element of claim 19, wherein the
2 second element material is thermally stable and a
3 transformation of the first element material is a result of
4 exposing the first element material to heat.

1 21. The interconnection element of claim 18, wherein the
2 first element material comprises the material having the
3 transformable property and the second element material has a
4 compressive stress, wherein upon transformation, the
5 deformation comprises a response to the compressive stress of
6 the second element material.

1 22. An electronic component comprising:
2 a substrate with a plurality of contact nodes; and

3 a plurality of free-standing resilient interconnection
 4 elements coupled to the substrate in such a manner that a
 5 base of an interconnection element electrically contacts a
 6 corresponding one of the contact nodes and an interconnection
 7 element comprises:

8 a first element material adapted to be coupled to a
 9 substrate, and

10 a second element material coupled to the first
 11 element material,

12 wherein one of the first element material and the second
 13 element material comprises a material having a transformable
 14 property such that upon transformation, a shape of the
 15 interconnection element is modified.

16 23. The electronic component of claim 22, further
 17 comprising:

18 a plurality of conductive signal lines associated with
 19 the substrate; and

20 in the plurality of free-standing resilient
 21 interconnection elements coupled to the substrate, the base
 22 of the interconnection element electrically contacts a
 23 corresponding one of the signal lines and an interconnection
 24 element.

25 24. The electronic component of claim 22, wherein a
 26 transformation of the one of the first element material and
 27 the second element material is irreversible.

28 25. The electronic component of claim 24, wherein the
 29 transformable property is such that a first volume of the
 30 second element material is adapted to be transformed to a
 31 different second volume.

1 26. The electronic component of claim 25, wherein a free
2 portion of the interconnection element is initially fixed to
3 the substrate and when the free portion is released from the
4 substrate, the free portion is adapted to be biased away from
5 the substrate in response to a transformation of the second
6 element material from the first volume to the second volume.

1 27. The electronic component of claim 26, wherein the first
2 element material and the second element material of the
3 interconnection element are arranged in a configuration such
4 that the second element material overlies the first element
5 material and the first volume is greater than the second
6 volume.

1 28. The electronic component of claim 27, wherein the first
2 element material is thermally stable and a transformation of
3 the second element material from the first volume to the
4 second volume is a result of exposing the second element
5 material to heat.

1 29. The electronic component of claim 28, wherein the
2 transformation comprises at least 90 percent of a
3 transformable volume change of the second element material.

1 30. The electronic component of claim 22, wherein each of
2 the first element material and the second element material
3 have a transformable property.

1 31. The electronic component of claim 22, wherein at least
2 one of the first element material and the second element
3 material are introduced by plating.

1 32. The electronic component of claim 22, wherein at least
2 one of the first element material and the second element
3 material are introduced by sputtering.

1 33. The electronic component of claim 22, wherein the first
2 element material comprises palladium.

1 34. The electronic component of claim 22, wherein the second
2 element material overlies the first element material and each
3 interconnection element further comprises a spring material
4 coupled to the second element material, the spring material
5 comprising at least about 90 percent of the interconnection
6 element.

1 35. The electronic component of claim 34, wherein the spring
2 material comprises a nickel alloy.

1 36. The electronic component of claim 34, wherein the
2 interconnection element further comprises a contact material
3 adjacent a surface of the spring material.

1 37. The electronic component of claim 22, wherein the one of
2 the first element material and the second element material
3 comprises a shape memory alloy.

1 38. The electronic component of claim 22, wherein the
2 transformable property is a stress and the transformation
3 reduces the magnitude of the stress of the material.

1 39. The electronic component of claim 38, wherein the first
2 element material comprises the material having the
3 transformable property and the second element material has a
4 tensile stress, wherein upon transformation, the deformation
5 comprises a response to the tensile stress of the second
6 element material.

1 40. The electronic component of claim 39, wherein the second
2 element material is thermally stable and a transformation of
3 the first element material is a result of exposing the first
4 element material to heat.

1 41. The electronic component of claim 38, wherein the first
2 element material comprises the material having the
3 transformable property and the second element material has a
4 compressive stress, wherein upon transformation, the
5 deformation comprises a response to the compressive stress of
6 the second element material.

1 42. The electronic component of claim 22, wherein the
2 plurality of free standing interconnection elements are
3 coupled to more than one surface of the substrate.

1 43. The electronic component of claim 22, wherein the
2 plurality of nodes comprise a first contact points, the
3 electronic assembly further comprising:

4 at least one re-distribution line coupled to at least
5 one of the plurality of nodes,

6 wherein the corresponding at least one interconnection
7 element is coupled to a second contact point different from
8 the first contact point, the second contact point and the
9 first contact point coupled through the at least one re-
10 distribution line.

1 44. The electronic component of claim 22, wherein the
2 substrate comprises one of a semiconductor, a ceramic, an
3 organic, and a metal material.

1 45. The electronic component of claim 22, wherein the
2 substrate comprises an interposer.

1 46. The electronic component of claim 22, wherein the
2 substrate comprises a component of a probe card.

1 47. The electronic component of claim 22, wherein the
 2 substrate comprises a socket for releasably connecting the
 3 electronic assembly to an electronic component.

Sub 46 1 48. An assembly comprising:

2 a first substrate having a plurality of first contact
 3 nodes formed on the first substrate and a plurality of free-
 4 standing resilient interconnection elements coupled to the
 5 substrate in such a manner that a base of an interconnection
 6 element electrically contacts a corresponding one of the
 7 first contact nodes; and

8 a second substrate having a plurality of second contact
 9 nodes,

10 wherein the interconnection element comprises:

11 a first element material adapted to be coupled to a
 12 substrate, and

13 a second element material coupled to the first
 14 element material, and one of the first element material and
 15 the second element material comprises a material having a
 16 transformable property such that upon transformation, a shape
 17 of the interconnection element is modified,

18 wherein the interconnection element has a portion
 19 thereof which is capable of moving to a first position in
 20 which the interconnection element is in contact with a second
 21 contact node.

1 49. The assembly of claim 48, wherein the assembly is part
 2 of a probe card assembly.

Cont Sub D1 1 50. The assembly of claim 48, wherein the assembly is part
 2 of a wafer-level test assembly.

1 51. The assembly of claim 48, wherein the second substrate
 2 is a circuit board.

1 52. The assembly of claim 48, wherein the assembly is part
 2 of a socket and the second contact nodes comprise external
 3 connection points.

1 53. The assembly of claim 52, further comprising a third
2 substrate of a circuit board having a plurality of third
3 contact nodes,

4 wherein the external connection are aligned with the
5 third contact nodes to couple the package to the third
6 substrate.

1 54. The assembly of claim 48, further comprising a stop
2 structure disposed on the first substrate and defining the
3 first position.

1 55. The assembly of claim 48, wherein a transformation of
2 the one of the first element material and the second element
3 material is irreversible.

1 56. The assembly of claim 55, wherein the transformable
2 property is such that a first volume of the material is
3 adapted to be transformed to a different second volume.

1 57. The assembly of claim 56, wherein a free portion of the
2 interconnection element is initially fixed to the first
3 substrate and when the free portion is released from the
4 first substrate, the free portion is adapted to be biased
5 away from the first substrate in response to a transformation
6 of the second element material from the first volume to the
7 second volume.

1 58. The assembly of claim 57, wherein the first element
2 material and the second element material of the
3 interconnection element are arranged in a configuration such
4 that the second element material overlies the first element
5 material and the first volume is greater than the second
6 volume.

1 59. The assembly of claim 58, wherein the first element
2 material is thermally stable and a transformation of the

3 second element material from the first volume to the second
4 volume is a result of exposing the second element material to
5 heat.

1 60. The assembly of claim 59, wherein the transformation
2 comprises at least 90 percent of a transformable volume
3 change of the second element material.

1 61. The assembly of claim 48, wherein each of the first
2 element material and the second element material have a
3 transformable property.

1 62. The assembly element of claim 48, wherein at least one
2 of the first element material and the second element material
3 are introduced by plating.

1 63. The assembly of claim 48, wherein at least one of the
2 first element material and the second element material are
3 introduced by sputtering.

1 64. The assembly of claim 48, wherein the first element
2 material comprises palladium.

1 65. The assembly of claim 48, wherein the second element
2 material overlies the first element material and
3 interconnection element further comprises a spring material
4 coupled to the second element material, the spring material
5 comprising at least about 90 percent of the interconnection
6 element.

1 66. The assembly of claim 65, wherein the spring material
2 comprises a nickel alloy.

1 67. The assembly of claim 65, wherein the interconnection
2 element further comprises a contact material adjacent a
3 surface of the spring material.

1 68. The assembly of claim 48, wherein the one of the first
2 element material and the second element material comprises a
3 shape memory alloy.

1 69. The assembly of claim 48, wherein the transformable
2 property is a compressive stress and the transformation
3 reduces the compressive stress of the material.

1 70. The assembly of claim 69, wherein the first element
2 material comprises the material having the transformable
3 property and the second element material has a tensile
4 stress, wherein upon transformation, the deformation
5 comprises a response to the tensile stress of the second
6 element material.

1 71. The assembly of claim 70, wherein the second element
2 material is thermally stable and a transformation of the
3 first element material is a result of exposing the first
4 element material to heat.

1 72. The assembly of claim 69, wherein the first element
2 material comprises the material having the transformable
3 property and the second element material has a compressive
4 stress, wherein upon transformation, the deformation
5 comprises a response to the compressive stress of the second
6 element material.

1 73. The assembly of claim 48, wherein the plurality of free
2 standing interconnection elements are coupled to more than
3 one surface of the substrate.

1 74. The assembly of claim 48, wherein each of the plurality
2 of first contact nodes on the first substrate terminate at
3 first contact points, the electronic assembly further
4 comprising:

5 at least one re-distribution line coupled to at least
6 one of the plurality of first contact nodes,

7 wherein the corresponding at least one interconnection
8 element is coupled to a second contact point different from
9 the first contact point, the second contact point and the
10 first contact point coupled through the at least one re-
11 distribution line.

1 75. The assembly of claim 48, wherein the first substrate
2 comprises one of a semiconductor, a ceramic, an organic, and
3 a metal material.

1 76. A system for contacting an electronic device including
2 an assembly comprising:
3 a first substrate having a plurality of first contact
4 nodes formed on the first substrate and a plurality of free-
5 standing resilient interconnection elements coupled to the
6 substrate in such a manner that a base of an interconnection
7 element electrically contacts a corresponding one of the
8 first contact nodes; and
9 a second substrate having a plurality of second contact
10 nodes,

11 wherein the interconnection element comprises:

12 a first element material adapted to be coupled to a
13 substrate, and

14 a second element material coupled to the first
15 element material, and one of the first element material and
16 the second element material comprises a material having a
17 transformable property such that upon transformation, a shape
18 of the interconnection element is modified,

19 wherein the interconnection element has a portion
20 thereof which is capable of moving to a first position in
21 which the interconnection element is in contact with a second
22 contact node.

1 77. The system of claim 76, wherein the system comprises an
2 integrated circuit test system and the assembly is part of a
3 probe card assembly.

1 78. The system of claim 76, wherein the system is a
2 substrate mounting system.

1 79. The system of claim 78, wherein the second substrate is
2 a circuit board.

1 80. The system of claim 78, wherein the assembly is part of
2 a socket and the second contact nodes comprise external
3 connection points.

1 81. The system of claim 80, wherein the assembly further
2 comprises a third substrate of a circuit board having a
3 plurality of third contact nodes,

4 wherein the external connection are aligned with the
5 third contact nodes to couple the package to the third
6 substrate.

1 82. The system of claim 76, further comprising a stop
2 structure disposed on the first substrate and defining the
3 first position.